

#### ABSTRACT OF THE DISCLOSURE

A semiconductor device using a lead frame as a wiring base member, in which a plurality of lead electrodes connected to a semiconductor chip through a connecting lead are arranged  
5 around the semiconductor chip having an upper surface and an under surface, and the semiconductor chip, connecting means and lead electrodes are integrally sealed. Each of the lead electrodes includes a thin internal lead portion having a connection part with the connecting means on the upper surface  
10 side, and a thick external electrode portion protruding toward the under surface side to form a connection part to outside. The seal resin layer has an underside which forms substantially the same surface as the under surface of the internal lead portion of the lead electrodes, and the external electrode  
15 portion protrudes downward from the underside of the seal resin layer.